

(1.00 mm) .0394"

MEC1 SERIES

MINI EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC1

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Sn or Au over 50 μ "

(1.27 μ m) Ni

Operating Temp Range:

-55 °C to +125 °C

Current Rating:

2.2 A per pin

(2 adjacent pins powered)

Voltage Rating:

300 VAC

Insertion Depth:

(5.84 mm) .230" to

(8.13 mm) .320"

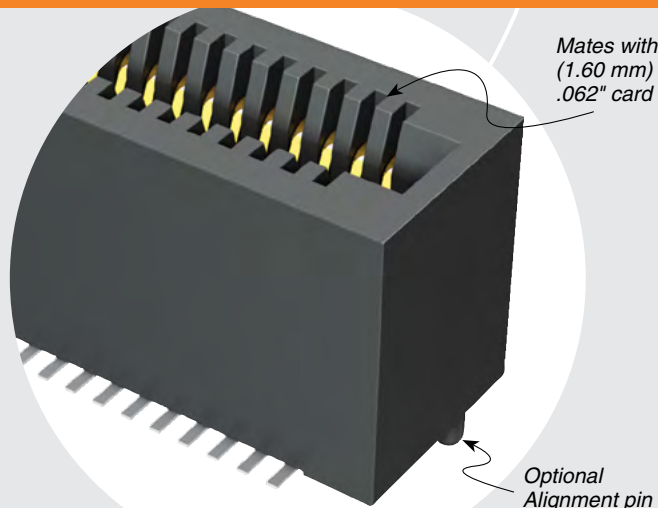
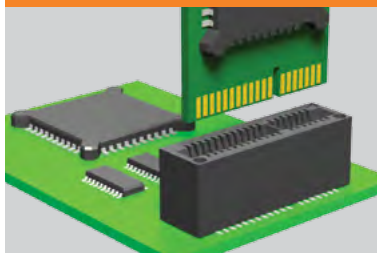
RoHS Compliant:

Yes

Mates with:

(1.60 mm) .062" card

APPLICATION



PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (05-20)

(0.15 mm) .006" max (30-70)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Locking Clip (Manual placement required)
- Other platings
- Contact Samtec.

Important Note:

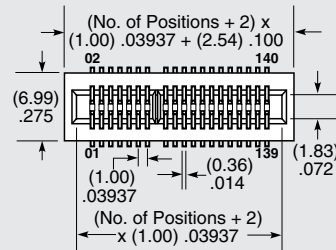
Samtec recommends that pads on the mating board be Gold plated.

Notes:

While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications. Contact Samtec for further information.

Some sizes, styles and options are non-standard, non-returnable.

MEC1	1	POSITIONS PER ROW	02	PLATING OPTION	D	NP	OTHER OPTION
05, 08, 20, 30, 40, 50, 60, 70				-F = Gold flash on contact, Matte tin on tail -L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail	-NP = No Polarization (05, 08, 20 & 30 positions only) Leave Blank for polarization	-A = Alignment Pin metal or plastic at Samtec discretion. -K = (7.87 mm) .310" DIA Polyimide film Pick & Place Pad -TR = Tape & Reel (05-60 only)	



POSITIONS PER ROW	POLARIZED POSITIONS (No Contact)
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116

